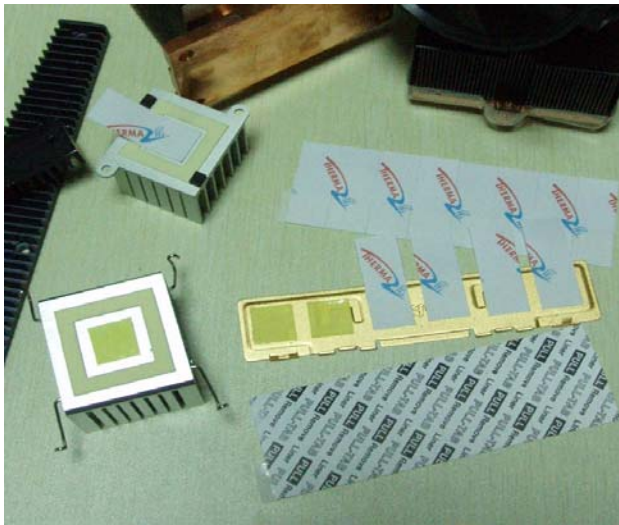


Low Melting Point Thermal Interface Materials

TIC™800Y Series is low melting point thermal interface material. At 50 °C, TIC™800Y series begins to soften and flow, filling the microscopic irregularities of both the thermal solution and the integrated circuit package surface, thereby reducing thermal resistance. TIC™800Y series is a flexible solid at room temperature and freestanding without reinforcing components that reduce thermal performance.

TIC™800Y Series shows no thermal performance degradation after 1,000 hours @ 130 °C, or after 500 cycles, from -25 °C to 125 °C. The material softens and does not fully change state resulting in minimal migration (pump out) at operating temperatures.



低熔點導熱界面材料

TIC™800Y系列是一種高性能低熔點導熱界面材料。在溫度50°C，TIC™800Y開始軟化並流動，填充散熱片和積體電路板的接觸介面上細微不規則間隙，以達到減小熱阻的目的。TIC™800Y系列在室溫下呈可彎曲固態，無需增強材料而獨立使用，免除了增強材料對熱傳導性能的影響。

TIC™800Y系列在溫度130°C下持續1000小時，或經歷-25°C到125°C的反覆循環測試，其導熱性能仍不會減退。在工作溫度下，其中相變材料軟化的同時又不會完全液化或溢出。

For Lowest Thermal Resistance :

- › **0.021°C-in² /W** thermal resistance
- › Naturally tacky at room temperature, no adhesive required
- › No heat sink preheating required

Applications Include:

- › High Frequency Microprocessors
- › Notebook and Desktop PCs
- › Computer Servers
- › Memory Modules
- › Cache Chips
- › IGBTs

最小熱阻系列:

- › **0.021°C-in² /W** 熱阻
- › 室溫下具有天然黏性, 無需黏合劑
- › 散熱器無需預熱

適用於:

- › 高頻率微處理器
- › 筆記本和桌上型電腦
- › 電腦伺服器
- › 記憶體模組
- › 快取記憶體晶片
- › IGBTs

Gap Fillers | Phase Change Materials | Thermally Conductive Insulators | Thermally Conductive PCB Materials | Greases | Thermally Conductive Adhesive Tapes

Typical Properties of TIC™800Y Series
TIC™800Y 系列特性表

Product Name (產品名稱)	TIC™803Y	TIC™805Y	TIC™808Y	TIC™810Y	Test Method (測試標準)
Color (顏色)	Yellow (黃)	Yellow (黃)	Yellow (黃)	Yellow (黃)	Visual (目視)
Thickness (厚度)	0.003" (0.076mm)	0.005" (0.126mm)	0.008" (0.203mm)	0.010" (0.254mm)	
Thickness Tolerance (厚度公差)	±0.0006" (±0.016mm)	±0.0008" (±0.019mm)	±0.0008" (±0.019mm)	±0.0012" (±0.030mm)	
Density (密度)	2.2g/cc				Helium Pycnometer
Temperature range (工作溫度)	-25°C ~ 125°C				
Phase Change Softening Temperature (相變溫度)	50°C ~ 60°C				
"Burn In" Temperature (定型溫度)	70°C for 5 minutes				
Thermal Conductivity (熱傳導率)	0.95 W/mK				ASTM D5470 (modified)
Thermal Impedance (熱阻抗) @ 50 psi(345 KPa)	0.021°C-in²/W	0.024°C-in²/W	0.053°C-in²/W	0.080°C-in²/W	ASTM D5470 (modified)
	0.14°C-cm²/W	0.15°C-cm²/W	0.34°C-cm²/W	0.52°C-cm²/W	

Standard Thicknesses(標準厚度):

0.003"(0.076mm) 0.005"(0.127mm) 0.008"(0.203mm) 0.010"(0.254mm)

Consult the factory alternate thickness.(如需不同厚度請與本公司聯繫。)

Standard Sizes(標準尺寸):

10" x 16"(254mm x 406mm) 16" X 400' (406mm X 121.92M)

TIC™800 series are supplied with a white release paper and a bottom liner. TIC™800 series is available in kiss cut an extended pull tab liner or individual die cut shapes.

(TIC™800 系列片料供應時附有白色離型紙及底襯墊，模切半斷加工可提供拉手,也可提供模切成單個形狀型試提供。)

Peressure Sensitive Adhesive(壓敏黏合劑):

Peressure Sensitive Adhesive is not applicable for TIC™800 series products.(壓敏黏合劑不適用於TIC™800 系列產品。)

Reinforcement(補強材料):

No reinforcement is necessary.(無需補強材料。)